

Materials List for:

Origami Inspired Self-assembly of Patterned and Reconfigurable Particles

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Materials

Name	Company	Catalog Number	Comments
950 Poly methyl methacrylate A11	Micro Chem	M230011	Sacrificial layer
Chromium-plated tungsten rods	R. D. Mathis Company	CRW-2	Evaporation source for Cr
Copper slug	Alfa Aesar	7440-50-8	Evaporation source for Cu
Gold slug	Alfa Aesar	7440-57-5	Evaporation source for Au
SPR 220 7.0	Rohm and Haas	10016640	Positive photoresist
S 1800 series photoresists	Rohm and Hass		Positive photoresist
Megaposit MF- 26 A developer	Rohm and Haas	10016574	Developer for SPR 220 7.0 photoresist
Microposit 351 developer	Rohm and Hass	10016653	Developer for S 1800 series photoresists
Nickel Sulfamate	Technic Inc.	030175	Plating solution for Ni
Techni Solder Mate NF 820 60/40 RTU	Technic Inc.	330681	Plating solution for Pb-Sn hinges
APS 100 Copper etchant	Transene Company Inc.	021221	Copper etchant
CRE 473 Chromium etchant	Transene Company Inc.	040901	Chromium etchant
1-Methyl-2-Pyrrolidinone (NMP)	Sigma-Aldrich	M79603	High boiling point organic solvent for Pb-Sn hinge based self-folding
Indalloy 5RMA flux	Indium Corporation of America	FL28372	Chemical that cleans the solder surface and inhibits oxidation for good Pb-Sn reflow